

L Number	Hits	Search Text	DB	Time stamp
1	21	3484534.URPN.	USPAT	2004/01/03 12:24
-	2	(leadframe).ti. and (harrison).in.	USPAT; US-PGPUB; EPO; JPO	2003/06/26 17:08
-	9	("4743956" "4974053" "5115298" "5138430" "5200364" "5313102" "5397916" "5457340" "5569956").PN.	USPAT	2003/06/26 17:05
-	1387	lead\$1frame and encapsulat\$3	USPAT; EPO; JPO	2003/06/26 17:09
-	76	(lead\$1frame and encapsulat\$3) and conductive adj1 pad	USPAT; EPO; JPO	2003/06/26 17:40
-	535	encapsulat\$3 and print\$3 and lead and conductive adj1 pad	USPAT; EPO; JPO	2003/06/26 17:41
-	3	("4575748" "4578697" "4789889").PN.	USPAT	2003/08/04 13:14
-	360	29/827,832,840,841,838,839.ccls. and lead\$1frame	USPAT; EPO; JPO	2003/08/04 13:56
-	155	(29/827,832,840,841,838,839.ccls. and lead\$1frame) and encapsulat\$3	USPAT; EPO; JPO	2003/08/04 13:57
-	6	257/666-676.ccls. and lead\$1frame and arcuate	USPAT; US-PGPUB	2003/08/04 14:52
-	6	257/666-676.ccls. and lead\$1frame and arcuate	USPAT; EPO; JPO	2003/08/04 14:52
-	42	257/666-676.ccls. and lead\$1frame and spacing and constant	USPAT; EPO; JPO	2003/08/04 16:08
-	8	("3680206" "3936930" "3971610" "4000054" "4116517" "4403272" "4758459" "4813129").PN.	USPAT	2003/08/04 16:07
-	1	4453795.pn.	USPAT; EPO; JPO	2003/08/04 16:08
-	45	5313096.URPN.	USPAT	2003/08/04 16:20
-	55	5200362.URPN.	USPAT	2003/08/04 16:37
-	9	("4743956" "4974053" "5115298" "5138430" "5200364" "5313102" "5397916" "5457340" "5569956").PN.	USPAT	2003/08/04 18:03
-	9	("3142783" "3266125" "3484534" "3792383" "4064552" "4095412" "4144705" "4157007" "4241436").PN.	USPAT	2004/01/02 18:45
-	4	4,142,287.pn. 4,405,242.pn.	USPAT; EPO; JPO	2004/01/02 18:47
-	21	3484534.URPN.	USPAT	2004/01/02 18:48
-	19	3617819.URPN.	USPAT	2004/01/02 18:50
-	10	3746932.URPN.	USPAT	2004/01/02 18:51

US Full Image

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current
5	✓	✓	US 4974053 A	19901127	22	Semiconductor device for multiple packaging	257/666	257/786; 257/E23.
6	✓	✓	US 4743956 A	19880510	5	Offset bending of curvaceously planar	257/674	216/14; 257/E23.
7	✓	✓	US 5158466 A	19921027	6	Metallically encapsulated elevated interconnection	439/67	29/846; 439/86
8	✓	✓	US 5036380 A	19910730	9	Burn-in pads for tab interconnects	257/668	257/48; 257/735;
9	✓	✓	US 4774635 A	19880927	8	Semiconductor package with high density I/O lead	361/813	174/52.4 257/676;
10	✓	✓	US 4598337 A	19860701	8	Electronic circuit board for a timepiece	361/763	361/749; 368/318;
11	✓	✓	US 5589402 A	19961231	9	Process for manufacturing a package for mating with a	438/64	257/E21.. 29/827;
12	✓	✓	US 5275975 A	19940104	9	Method of making a relatively flat	438/15	257/E23. 29/827;
13	✓	✓	US 5200362 A	19930406	7	Method of attaching conductive traces to an	29/841	257/E21.. 257/E23.
14	✓	✓	US 4807018 A	19890221	5	Method and package for dissipating heat generated	257/675	257/717; 257/E23.
15	✓	✓	US 5939775 A	19990817	27	Leadframe structure and process for packaging	257/667	257/671; 257/E21..
16	✓	✓	US 4453795 A	19840612	8	Cable-to-cable/component electrical pressure wafer	439/361	439/67
17	✓	✓	US 3484534 A	19691216	9	MULTILEAD PACKAGE FOR A MULTILEAD ELECTRICAL DEVICE	174/52.2	216/20; 257/735;
18	✓	✓	US 3746932 A	19730717	11	PANEL BOARD SYSTEMS AND COMPONENTS THEREFOR	361/785	174/52.4 257/E23.
19	✓	✓	US 4514750 A	19850430	9	Integrated circuit package having interconnected leads	257/670	174/52.4 257/E23.

[Details](#)
[Text](#)
[Image](#)
[HTML](#)